ECOREL[™] FREE HT 245-16







High Melting Point Lead Free Halogen free solder paste

BENEFITS

ECOREL[™] **FREE HT 245-16** is a no clean solder paste using Tin-Antimony (SnSb8.5) alloy.

- Higher melting point (241° to 248°C) compared to the standard SAC alloys.
- Suitable for hybrid, microelectronics or stacking assemblies where a higher melting point may be required in first soldering process.
- It can suit electronics assemblies operating close to 200°C.

SPECIFICATIONS

Alloy	SnSb8.5
Particle size (microns) / Type	20 – 38 / Type 4
Melting point (°C)	241 - 248
Metal content (%)	88 +/- 0.5
Halogen content	No Halogen
Viscosity* (Pa.s 20°C) *Brookfield RVT - TF at 5 rpm	800 – 1000
Post reflow residues	Approximately 5% by w/w

CHARACTERISTICS

The radar chart below shows the excellent printing capabilities of **ECORELTM FREE HT 245-16** which allows for high speed printing, excellent abandon time, and long, steady tackiness. Its large process window allows for good soldering of medium and large boards with a wide range of component sizes.

High performance in pin in paste process

Fine pitch printing

Pin in paste

Chemical reliability

Residue cleanliness

ICT / FP Test

Cosmetic residue

Tombstoning

Solder beading

Fine pitch printing

Printing speed

Stencil life

Abandon time

Hot slump

Reflow process window

Wettability

Standards tests	Results	Procedures	
Flux Classification	ROL0	ANSI/J-STD-004	
	113	ISO 9454	
Solder balling test	pass	ANSI/J-STD-005	
Copper mirror	pass	ANSI/J-STD-004	
Chromate paper	pass	ANSI/J-STD-004	
Copper corrosion	pass	ANSI/J-STD-004	
SIR (IPC)	pass	ANSI/J-STD-004	
SIR (Bellcore)	pass	Bellcore	
Electromigration (IPC / Bellcore)	pass	ANSI/J-STD-004 / Bellcore	
Oxygen bomb test	pass	EN 14582	

PROCESS PARAMETERS

Store at room temperature at least four hours before use.

Solder paste preparation

Before printing, it is essential to properly mix the solder paste, either manually with a spatula, or by doing several preliminary prints on the stencil.

Printing guideline

Apply on the stencil solder paste to form a roll of 1 to 2cm of diameter all along the squeegee or around 100g per 10cm of squeegee length. This way, the solder paste will roll easily under the squeegees to offer excellent printing quality

Printing speed: 20 to 150mm/s (1 to 6in/s)

Minimum pitch: 0.3mm

Pressure depends on printing speed and printing equipment

Typical speed / pressure set up:

Squeegee length	Printing Speed	Pressure
	50 mm/s	4Kg
250	100 mm/s	6Kg
	150 mm/s	8Ka

- Stencil life > 12hrs in continuous printing process
- Abandon time > 4hrs as time between two prints with good re-start
- Steady tackiness > 16hrs

Reflow guideline

Linear preheating ramp rate is recommended. But high density board may require a soak zone during preheating to stabilize the temperature over the circuit board before peak reflow.

Preheating ramp rate with linear preheating	0.7 to 1.2°C/s according the circuit board size and density
Preheating steps in case of preheating soak zone	 From 20 to 150°C: ramp rate 1 to 2°C/s soak zone between 150 to 180°C for 60 to 140s from 170°C to liquidus 1 to 2°C/s
Peak ramp rate	1 to 2°C/s
Peak temperature	260 to 285°C It is recommended to verify components heat resistance to preserve their integrity.
Time above liquidus	40 to 90s

Cleaning

After soldering, the flux residue remaining of **ECORELTM FREE HT 245-16** does not have to be removed by a cleaning operation as it is chemically inert. However, if cleaning is required, the residue left after reflow can be easily removed if needed with a large range of cleaning solutions, such as detergents, hydro-carbonated solvents or halogenated solvents, all included in the INVENTEC cleaning range. This is also a best practice for a robust adhesion if conformal coating is to be applied on the board. In the table below is a quick reference about INVENTEC PCBA defluxing solutions.

PROCESS Type	INVENTEC PCBA Defluxing solutions	
Manual	Topklean [™] EL10F/ Topklean [™] EL60/ Quicksolv [™] DEF90 EL	
Aqueous System (Immersion or spray)	Promoclean [™] DISPER 607	
Novec [™] HFE + Co-solvent	Topklean [™] EL 20A and EL 20R	
Under Vacuum System	Topklean [™] EL 20D	
Azeotropic Solvent	Promosolv [™] 70ES	

PACKAGING, STORAGE & SHELF LIFE

To ensure the best product performance, the recommended storage temperature range is from 0°C to 10°C. For an optimal preservation, store cartridges and syringes in vertical position, tip downwards.

Jars	250g or 500g	12 months
Cartridges	600g or 1200g	9 months

HSE

No issues when used as recommended. Please refer to Material Safety Data Sheet before use. INVENTEC Material Safety Data sheets can be found at www.quickfds.com

Although the conformity to ROHS 2011/65UE applies EQUIPMENT put on the market and not a component in particular, we warranty that this product contains less than 0.1% of mercury, lead, chromium VI, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE) and less than 0.01% for the cadmium, in accordance with the decision of The European Commission dated 18/08/2005, fixing the maximal concentration values.

This data is based on information that the manufacturer believe to be reliable and offered in good faith. In no event will INVENTEC be responsible for special, incidental and consequential damages. The user is responsible to the Administrative Authorities (regulations for the protection of the Environment) for the conformity of his installation.

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